

TSG40N60

600 V, 40 A Field Stop IGBT

DRAWING

Features

- ◆ High Current Capability
- ◆ Low Saturation Voltage: $V_{CE(sat)} = 1.8\text{ V @ } I_C = 40\text{ A}$
- ◆ High Input Impedance
- ◆ Fast Switching
- ◆ RoHS Compliant

General Description

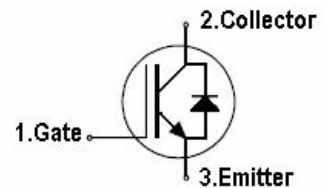
- ◆ Package: TO-247
- ◆ Using novel field stop IGBT technology, TS's field stop IGBTs offer the optimum performance for solar inverter, UPS, welder, microwave oven, telecom, ESS and PFC applications where low conduction and switching losses are essential.

Applications

Solar Inverter, UPS, Welder, PFC, Microwave Oven, Telecom, ESS



G C E



Absolute Maximum Ratings

Symbol	Parameter	Spec	Units
V_{CES}	Collector-Emitter Voltage	1200	V
V_{GES}	Gate-Emitter Voltage	± 20	V
	Transient Gate-to-Emitter Voltage	± 30	V
I_C	Collector Current ($T_C=25^\circ\text{C}$)	80	A
	Collector Current ($T_C=100^\circ\text{C}$)	40	A
I_{CM}	Pulsed Collector Current (Note 1) ($T_C=25^\circ\text{C}$)	120	A
P_D	Maximum Power Dissipation ($T_C=25^\circ\text{C}$)	290	W
	Maximum Power Dissipation ($T_C=100^\circ\text{C}$)	116	W
T_J	Operating Junction Temperature	-55 to +150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_L	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Note1: Repetitive rating: Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Spec	Units
$R_{\theta j-c}$	Thermal Resistance, Junction to case for IGBT	0.43	$^\circ\text{C/W}$
$R_{\theta j-c}$	Thermal Resistance, Junction to case for Diode	1.45	
$R_{\theta j-a}$	Thermal Resistance, Junction to Ambient	40	

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{CES}	Collector-Emitter Breakdown Voltage	$V_{GE}=0V, I_C=250\mu A$	600			V
BV_{DSS}/T_J	Temperature Coefficient of Breakdown Voltage	$I_D=250\mu A$, Referenced to 25°C	-	0.6	-	V/ $^\circ\text{C}$
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0V$			250	μA
I_{GES}	G-E Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0V$			± 400	nA
On Characteristics						
$V_{GE(th)}$	G-E Threshold Voltage	$I_C=250\mu A, V_{CE}=V_{GE}$	4.5	5.8	6.5	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE}=15V, I_C=40A$		$T_J=25^\circ\text{C}$ 1.8 $T_J=150^\circ\text{C}$ 2.0	2.4	V
Dynamic characteristics						
C_{ies}	Input Capacitance	$V_{CE}=30V$		2110		pF
C_{oes}	Output Capacitance	$V_{GE}=0V$		200		
C_{res}	Reverse Transfer Capacitance	$f=1\text{MHz}$		60		
IGBT switching characteristic(Inductive Load)						
$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=400V$ $I_C=40A$ $V_{GE}=15V$ $R_G=10\Omega$ Inductive Load $T_C=25^\circ\text{C}$		24		ns
t_r	Turn-on Rise Time			44		
$t_{d(off)}$	Turn-off Delay Time			112		
t_f	Turn-off Fall Time			30	60	
E_{on}	Turn-on Switching Loss	Inductive Load $T_C=25^\circ\text{C}$		1.19		mJ
E_{off}	Turn-off Switching Loss			0.46		
E_{ts}	Total Switching Loss			1.65		
$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=400V$ $V_{GE}=15V$ $I_C=40A$ $R_G=10\Omega$ Inductive Load $T_C=125^\circ\text{C}$		24		ns
t_r	Turn-on Rise Time			45		
$t_{d(off)}$	Turn-off Delay Time			120		
t_f	Turn-off Fall Time			40		
E_{on}	Turn-on Switching Loss	Inductive Load $T_C=125^\circ\text{C}$		1.2		mJ
E_{off}	Turn-off Switching Loss			0.69		
E_{ts}	Total Switching Loss			1.89		
Q_g	Total Gate Charge	$V_{CE}=400V$		120		nC
Q_{ge}	Gate to Emitter Charge	$V_{GE}=15V$		14		nC
Q_{gc}	Gate to Collector Charge	$I_C=40A$		58		nC

Electrical Characteristics of the Diode $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max	Unit
V_{FM}	Diode Forward Voltage	$I_F=20A$		$T_C=25^\circ\text{C}$ 1.95 $T_C=125^\circ\text{C}$ 1.85	2.6	V
t_{rr}	Diode Reverse Recovery Time	$I_F=20A,$		$T_C=25^\circ\text{C}$ 45 $T_C=125^\circ\text{C}$ 140		ns
Q_{rr}	Diode Reverse Recovery Charge	$diF/dt=200A/\mu s$		$T_C=25^\circ\text{C}$ 75 $T_C=125^\circ\text{C}$ 375		nC

Typical Characteristics

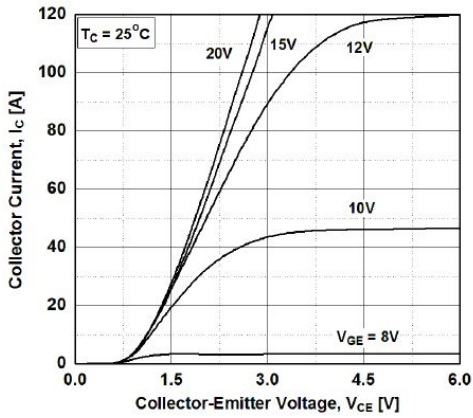


Figure 1. Typical Output Characteristics

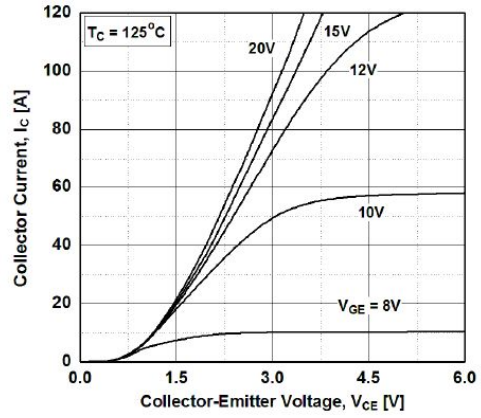


Figure 2. Typical Output Characteristics

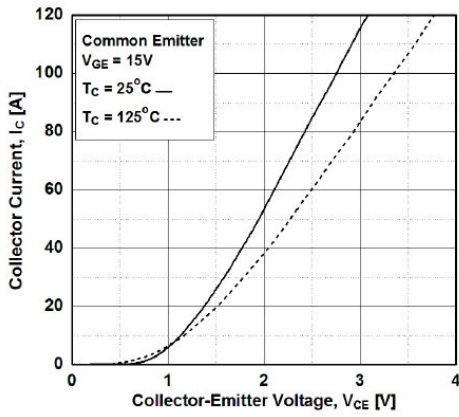


Figure 3. Typical Saturation Voltage Characteristics

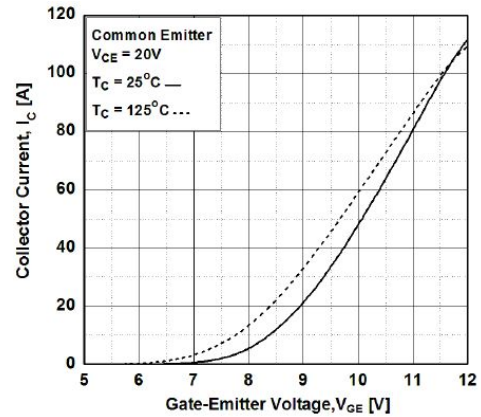


Figure 4. Transfer Characteristics

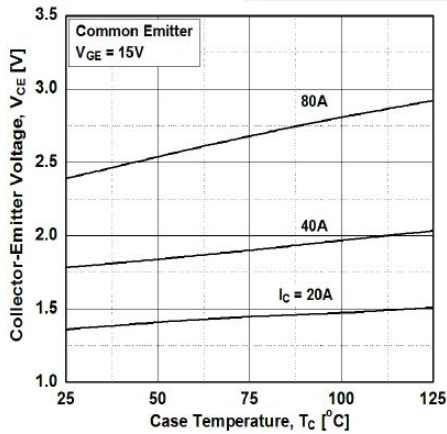


Figure 5. Saturation Voltage vs. Case Temperature at Variant Current Level

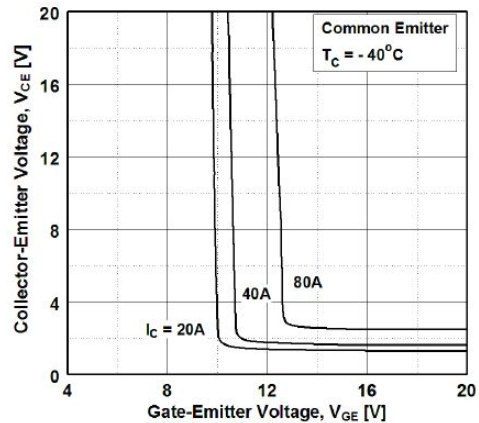


Figure 6. Saturation Voltage vs. VGE

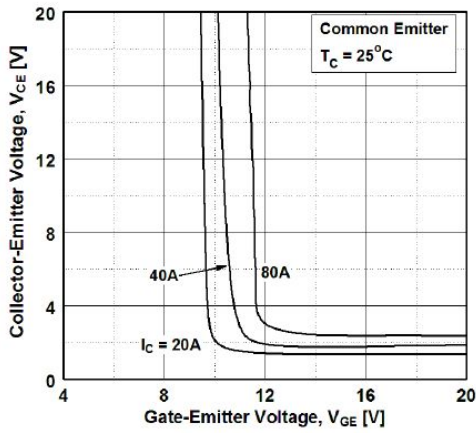


Figure 7. Saturation Voltage vs. VGE

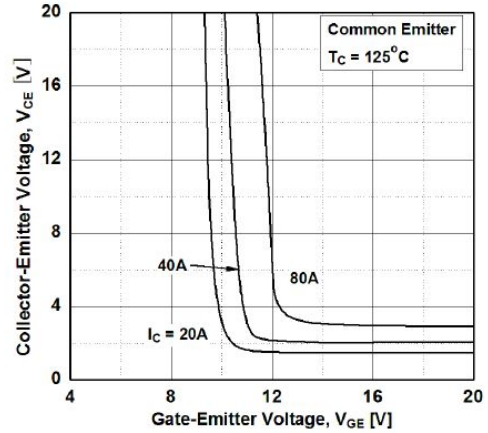


Figure 8. Saturation Voltage vs. VGE

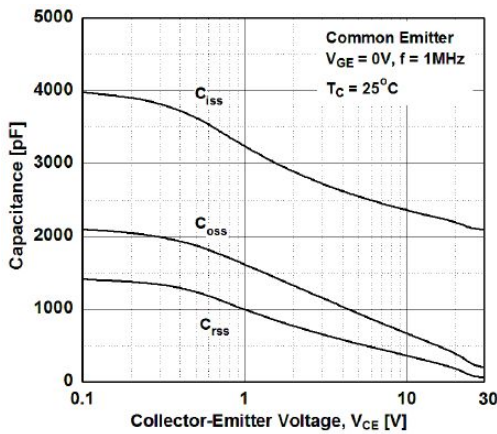


Figure 9. Capacitance Characteristics

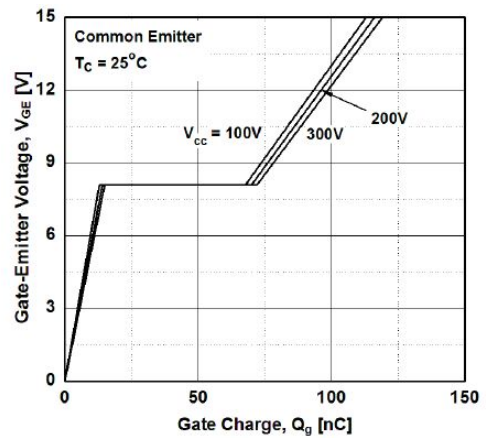


Figure 10. Gate charge Characteristics

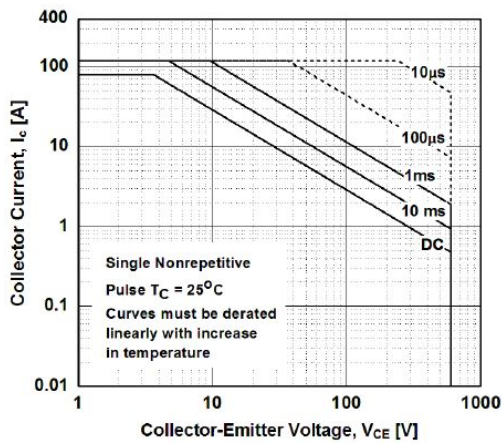


Figure 11. SOA Characteristics

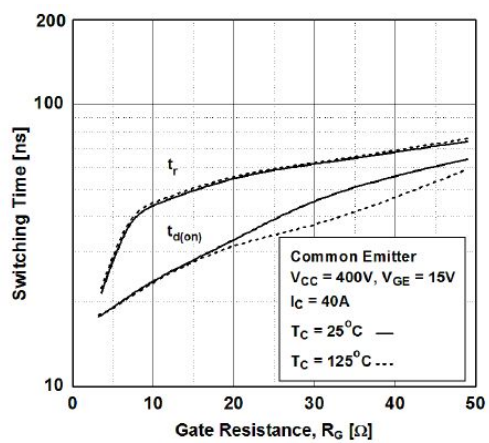


Figure 12. Turn-on Characteristics vs. Gate Resistance

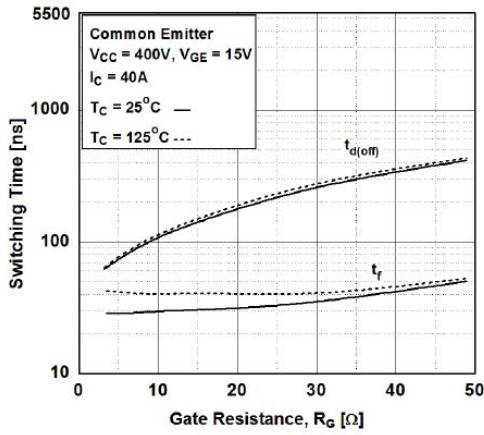


Figure 13. Turn-off Characteristics vs. Gate Resistance

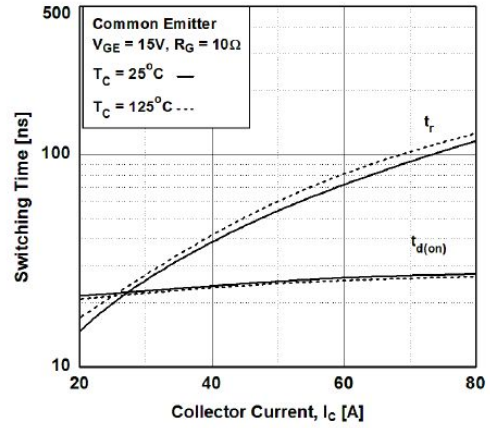


Figure 14. Turn-on Characteristics vs. Collector Current

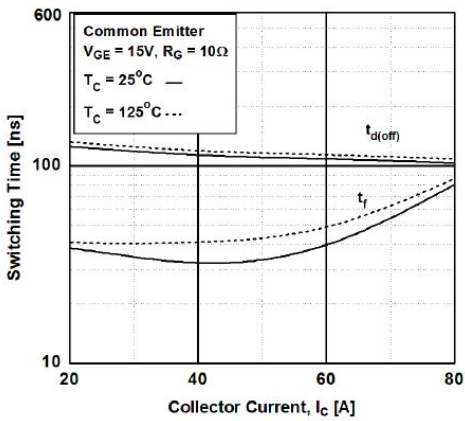


Figure 15. Turn-off Characteristics vs. Collector Current

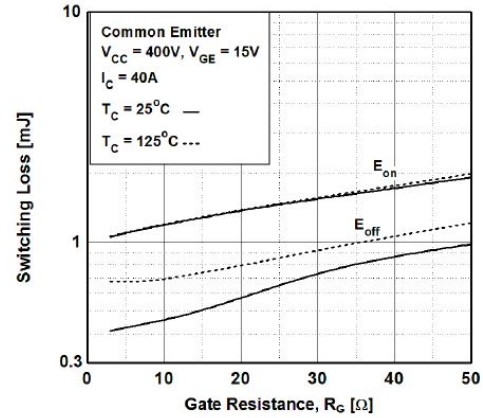


Figure 16. Switching Loss vs. Gate Resistance

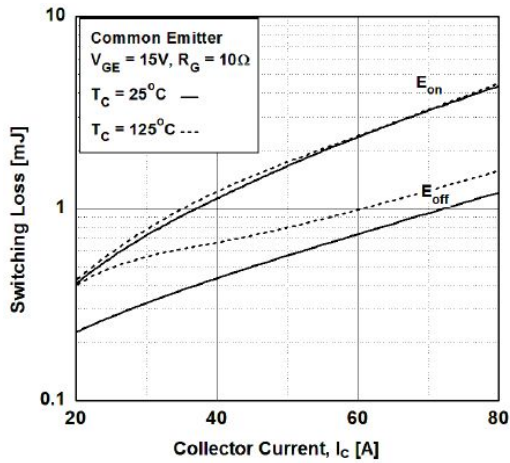


Figure 17. Switching Loss vs. Collector Current

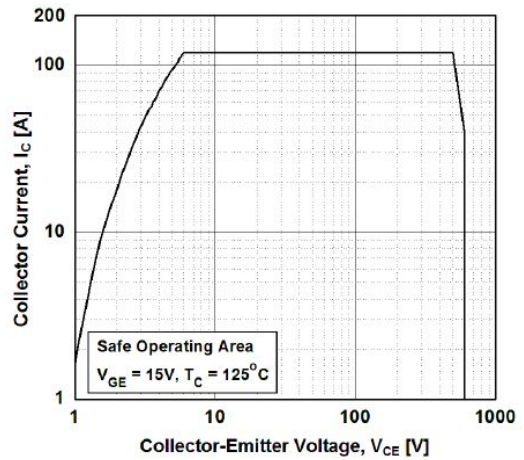


Figure 18. Turn off Switching SOA Characteristics

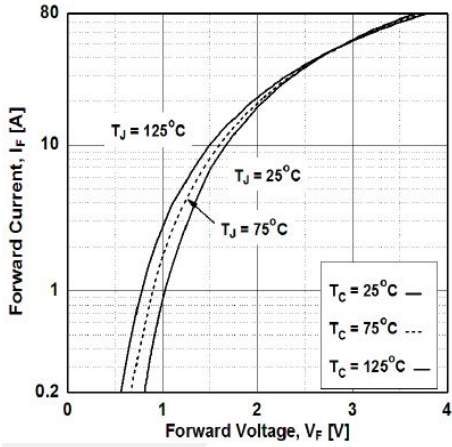


Figure 19. Forward Characteristics

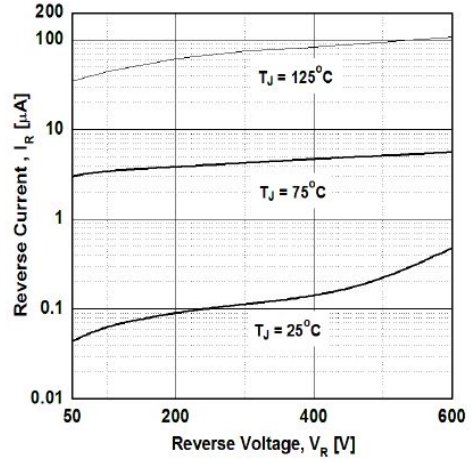


Figure 20. Reverse Current

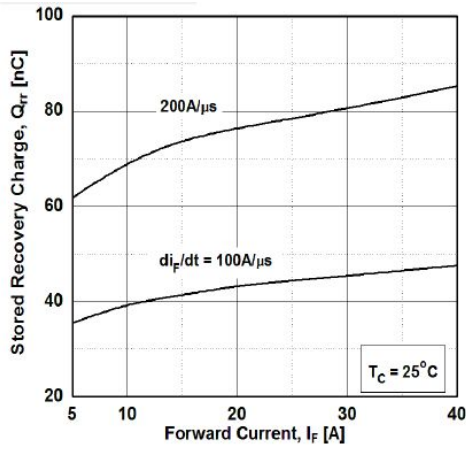


Figure 21. Stored Charge

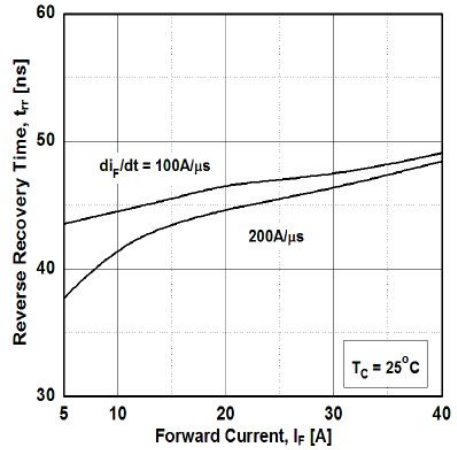


Figure 22. Reverse Recovery Time

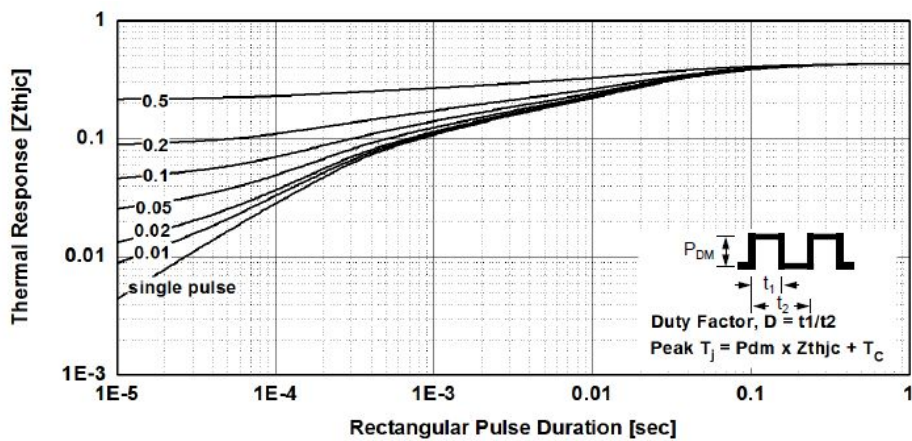


Figure 23. Transient Thermal Impedance of IGBT

Mechanical Dimensions

